



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



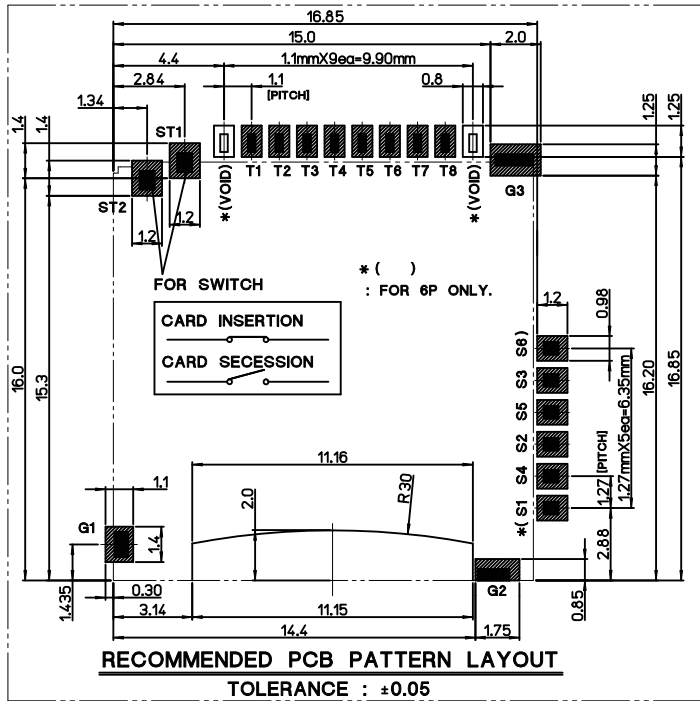
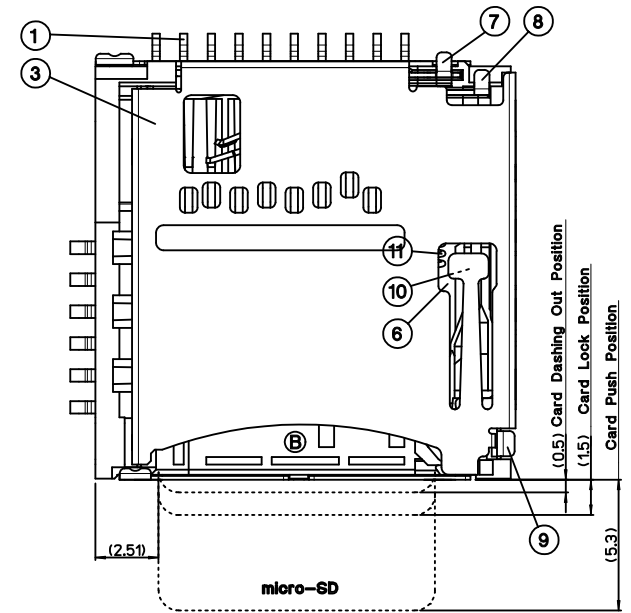
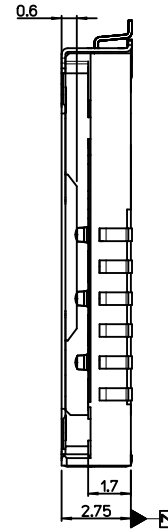
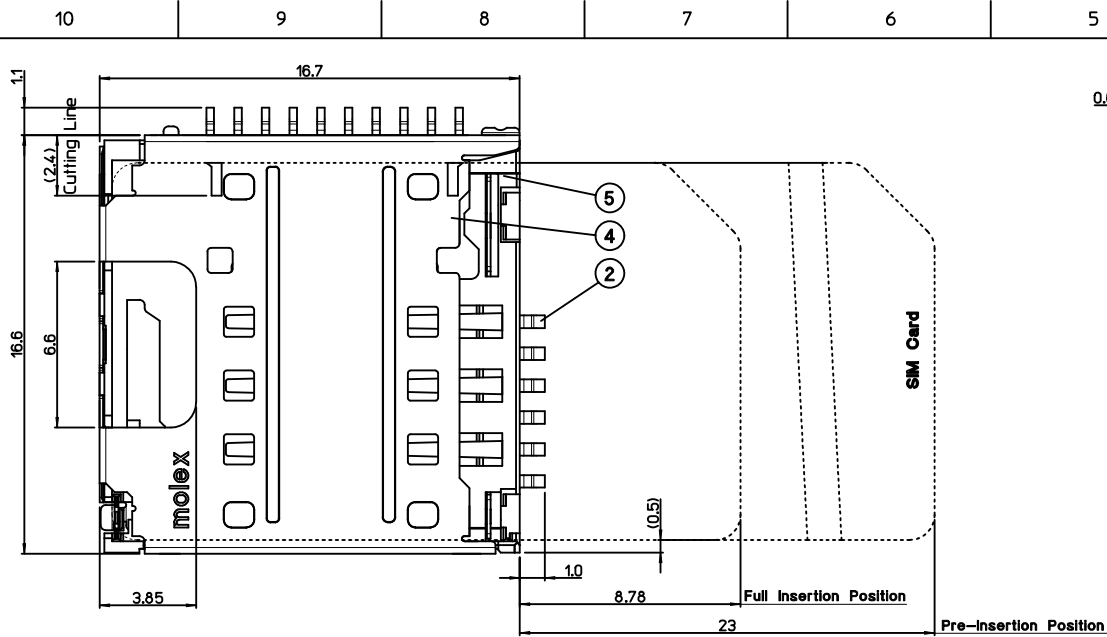
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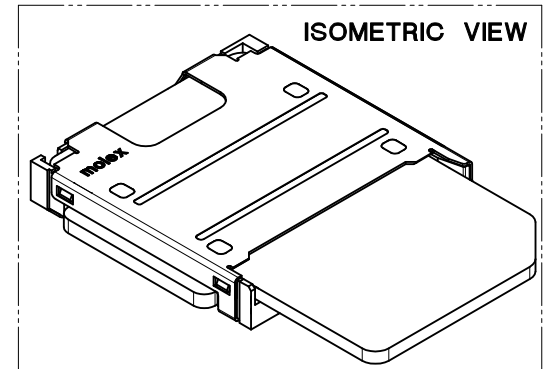


NOTES

1. MATERIALS: SEE TABLE 2
2. FINISHES: SEE TABLE 2
3. PRODUCT SPECIFICATION : PS-49448-001
4. COPLANARITY OF SOLDERTAILS : 0.1mm MAX.
MISALIGNMENT OF SOLDER TAIL FROM "Z"
UPPER DIRECTION 0.05 MAX., LOWER DIRECTION 0.1MAX.
5. PACKAGING SPECIFICATION : PK-49448-001

*** TABLE 1**

8P/6P	494481411	49448-1411
	MATERIAL NO.	ENGINEERING NO.



REVISED EC NO: KOR2011-0160 DRWN:HYOU CHKD:YSOOKIM APPR:YUNSIKKIM 2011/06/24 2011/06/24	QUALITY SYMBOLS ▽=0 ◁=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
				mm	INCH	DRAWN BY	DATE	TITLE		
		4 PLACES	± ---	± ---	IHYOU	2009/06/01	M-SD/SIM COMBO SOCKET FOR 8P/6P			
		3 PLACES	± ---	± ---	CHECKED BY	DATE				
2 PLACES	± 0.1	± ---	SHCHU	2009/06/01						
1 PLACE	± 0.15	± ---	APPROVED BY	DATE						
		ANGULAR ± 1 °		YSOOKIM	2009/06/01					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
				SD-49448-004		MOLEX INCORPORATED		1 OF 3		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										

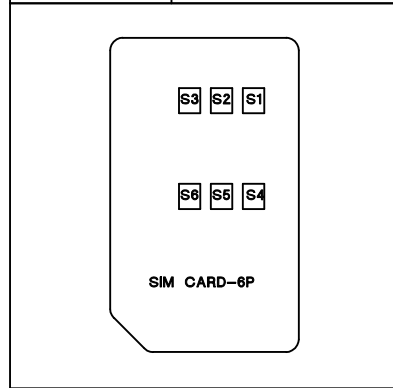
* TABLE 2 : PARTS-LIST

NO.	DESCRIPTION	ENGINEERING NO.	MATERIALS	FINISHES
1	mSD-CONTACT TERMINAL	49932-8031	PHOS.-BRONZE	Min. 0.2/0.05uM Au over Min. 1.27uM Ni Overall
2	S-CONTACT TERMINAL	49814-8031	Ⓢ COPPER-ALLOY	Min. 0.2/0.05uM Au over Min. 1.27uM Ni Overall
3	mSD-METAL SHELL	49933-5003	STAINLESS STEEL	Min. 0.7uM Ni Overall
4	S-METAL SHELL	49934-5003	STAINLESS STEEL	Min. 0.7uM Ni Overall
5	HOUSING	49448-1491	LIQUID CRYSTAL POLYMER	UL94V-0
6	HEART CAM	49383-0001	LIQUID CRYSTAL POLYMER	UL94V-0
7	SWITCH TERMINAL 1	49820-8031	PHOS.-BRONZE	Min. 0.1/0.05uM Au over Min. 1.27uM Ni Overall
8	SWITCH TERMINAL 2	49821-8031	PHOS.-BRONZE	Min. 0.1/0.05uM Au over Min. 1.27uM Ni Overall
9	FITTING NAIL	49819-8003	PHOS.-BRONZE	Min. 3.0uM Pure-Sn over Min. 1.27uM Ni Overall
10	PIN ROD	49225-9002	STAINLESS STEEL	
11	SPRING	49362-9001	STAINLESS STEEL	

* TABLE 3 : REFERENCE

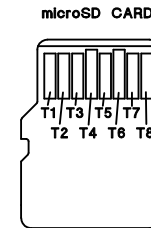
[SIM CARD-6P PIN-MAP]

PIN NUMBER	DESCRIPTION
S1	Vcc(Voltage)
S2	Vcc(Reset)
S3	CLK
S4	GND
S5	Vpp
S6	I/O

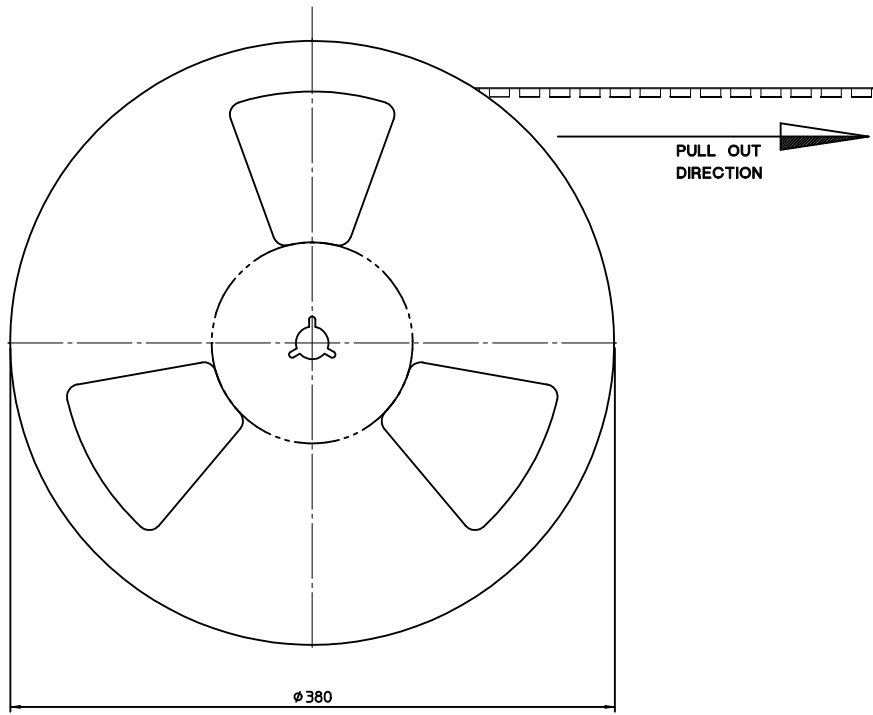


[microSD CARD PIN-MAP]

PIN NUMBER	DESCRIPTION
T1	DAT2
T2	CD/DAT3 ²
T3	CMD
T4	V _{DD}
T5	CLK
T6	V _{SS} ²
T7	DAT0
T8	DAT1

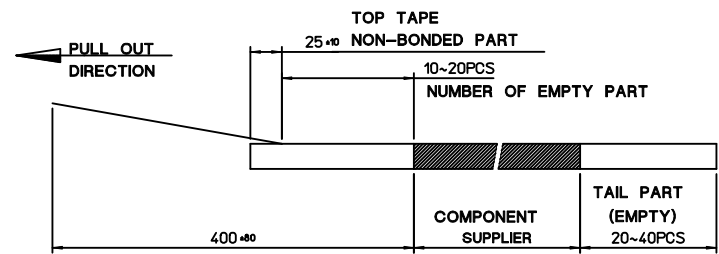


REVISED EC NO: KOR2011-0160 DRWN: IHYOU 2011/06/24 CHKD: YSOOKIM APPR: YUNS IKKIM 2011/06/24 DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.1 ± --- 1 PLACE ± 0.15 ± --- ANGULAR ± 1 °	DIMENSION STYLE MM ONLY DRAWN BY DATE IHYOU 2009/06/01 CHECKED BY DATE SHCHU 2009/06/01 APPROVED BY DATE YSOOKIM 2009/06/01 MATERIAL NO.	SCALE DESIGN UNITS METRIC THIRD ANGLE PROJECTION	TITLE M-SD/SIM COMBO SOCKET FOR 8P/6P	MOLEX INCORPORATED DOCUMENT NO. SD-49448-004	SHEET NO. 2 OF 3
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

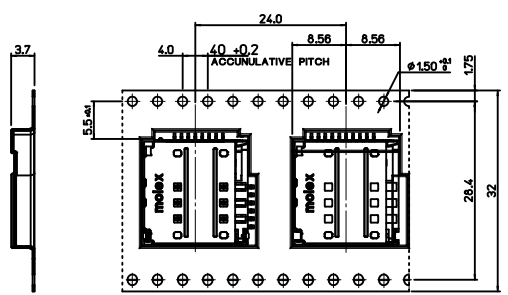


NOTES

1. QUANTITY OF CONNECTORS : 1,000PCS/REEL
2. LEAD LENGTH



3. PEELING OFF FORCE OF COVER TAPE : 0.1N~0.59N(10.2GF~60GF)
(PEELING DIRECTION AS SHOW IN FOLLOW FIG.)
- PEELING OFF SPEED : 300mm/Min.(Ref.)



35902-0011	35908-1003	49382-9901	49448-1411	494481411	49448-1411	8P/6P
COVER TAPE	REEL	EMBOSSSED TAPE	CONNECTOR	MATERIAL NO.	ENG. NO.	CKTS

PULL OUT DIRECTION

REVISED EC NO: KOR2011-0160 DRWN: IHYOU 2011/06/24 CHKD: YS00KIM APPR: YUNSIKKIM 2011/06/24	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY	DATE	TITLE	M-SD/SIM COMBO SOCKET FOR 8P/6P		
		4 PLACES	± ---	± ---	IHYOU	2009/06/01				
		3 PLACES	± ---	± ---	CHECKED BY	DATE				
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1 PLACE	± 0.15	± ---	APPROVED BY	DATE						
ANGULAR ± 1 °				YS00KIM	2009/06/01	MOLEX INCORPORATED				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
				A3		SD-49448-004		3 OF 3		
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